Hi-Rel SRAM MCP
Part Matrix

W X S XXX X XXX X V - XXX XXX X X X

MICROSEMI CORPORATION — 3 (1) position
- Blank = Multi-Chip Package
- M = Monolithic
- P = Plastic Multi-Chip Package

1 position

SRAM — 1 position

Number of Words — 3 (2, 1) positions

Word Factor — 1 position
- K = Kilo
- M = Mega

Bits per Word — 3 (2, 1) positions

Improvement Mark — 1 position
- L = Low Power for 2V Data Retention
- N = No Connect for HIP only

Voltage — 1 position
- Blank = 5V Power Supply
- V = 3.3V Power Supply

Access Times (ns) — 3 (2, 1) positions

Package Type/Pin Configuration — 3 (2, 1) positions

B	=	PBGA	G2U	=	68 CQFP (0.88” sq., 0.140” high)
C	=	32 DIP	G2S	=	68 CQFP (0.88” sq., 0.300” high)
CL	=	32 CLCC	G2T	=	68 CQFP (0.88” sq., 0.180” high)
DE	=	32 SOJ (Evol.)	G3	=	84 CQFP (1.07” sq., 0.169” high)
DR	=	32 SOJ (Revol.)	G4	=	68 CQFP (1.56” sq., 0.200” high)
DJ	=	36 SOJ	G4T	=	68 CQFP (1.56” sq., 0.140” high)
DL	=	44 SOJ	H	=	66 PGA (HIP), (1.185” sq.)
FE	=	32 Flatpack (Evol.)	H1	=	66 PGA (HIP), (1.075” sq.)
FR	=	32 Flatpack (Revol.)	H2	=	66 PGA (HIP), (1.385” sq.)
F	=	36 Flatpack w/Tie Bar	RJ	=	32 PSOJ
FL	=	44 Flatpack			
FG	=	44 Flatpack, Lead Formed			
G2L	=	68 CQFP (0.88” sq., 0.200” high)			

Device Grade — 1 position
- Q = MIL-PRF-38534 Compliant
- M = Military, screened -55°C to +125°C
- I = Industrial -40°C to +85°C
- C = Commercial 0°C to +70°C

Lead Finish — 1 position
- Blank = Gold plated leads
- A = Solder Dip leads

RoHS Compliant — 1 position
- G = RoHS Compliant
- Blank = Not RoHS Compliant

Note:

Not all packages, speeds and other options are available on every product.
Please refer to the individual data sheet for option selection.

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